

WHAT IS CLAIMED IS:

1. A carrier reel comprising: a flange portion having a first surface and a second surface which is opposed to and substantially parallel to said first surface; and a hub portion which is provided between said first surface and said second surface and to which said flange portion is connected, a carrier tape in which a plurality of electronic components are stored being wound around said hub portion, wherein accommodating portions accommodated therein a drying agent are provided to said hub portion.
2. The carrier reel according to claim 1, wherein a bearing portion associated with a shaft for supporting said flange portion from a direction ^{perpendicular} [vertical] to said flange portion is formed in the center of said hub portion and said accommodating portions are provided to said hub portion except said bearing portion.
3. The carrier reel according to claim 2, wherein said accommodating portions are provided symmetrical to said bearing portion.
4. The carrier reel according to claim 1, wherein said electronic component is a semiconductor device sealed by resin.

5. A carriage method using a carrier reel comprising:

winding a carrier tape in which a plurality of electronic components are stored, around a hub portion of said carrier reel, ^{the carrier wheel} including ^{STP} a flange portion having a first surface and a second surface which is opposed to and substantially parallel to said first surface, said hub portion ^{being} [which is] provided between said first surface and said second surface and ^{being connected} to [which] said flange portion [is connected], ^{STP} and accommodating portions which are provided ⁱⁿ [to] said hub portion [and accommodate therein a drying agent];

accommodating said drying agent in said accommodating portions; and

putting said carrier reel, around which said carrier tape is wound, into a bag and sealing said bag to perform carriage after accommodating said drying agent in said accommodating portions.

6. A carriage method using a carrier reel comprising :

winding a carrier tape in which a plurality of electronic components are stored around a hub portion of said carrier reel having a drying agent accommodated in accommodating portions provided to said hub portion, said carrier reel including a flange portion having a first surface and a second surface which is opposed to and substantially parallel to said first surface, and said hub

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putting said carrier reel around which said carrier
5 tape is wound into a bag and sealing said bag to perform
carriage.

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10. The carriage method according to claim 6, wherein said electronic component is a semiconductor device sealed by resin.

5 11. The carriage method according to claim 9, wherein at least 20 g or more of said drying agent is accommodated in said accommodating portions.

10 12. The carriage method according to claim 10, wherein at least 20 g or more of said drying agent is accommodated in said accommodating portions.

15 13. A method for manufacturing an electronic device according to claim 5 further comprising, taking out said carrier reel from said bag to mount said electronic component on a board after carriage of said carrier reel.

20 14. A method for manufacturing an electronic device according to claim 6 further comprising, taking out said carrier reel from said bag to mount said electronic component on a board after carriage of said carrier reel.

25 15. The method for manufacturing an electronic device according to claim 13, wherein said electronic component is a semiconductor device sealed by resin and said step of mounting said electronic component on said board is carried out by heat treatment.

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16. The method for manufacturing an electronic device according to claim 14, wherein said electronic component is a semiconductor device sealed by resin and said
5 step of mounting said electronic component on said board is carried out by heat treatment.

17. A carrier reel comprising:

10 a pair of flat plate portions arranged in substantially parallel to each other;
a drum portion to which a pair of said flat plate portions are connected;
a carrier tape which is wound around said drum portion and in which a plurality of semiconductor devices are
15 stored;
a bearing portion which is formed in the center of said drum portion and associated with a shaft supporting a pair of said flat plate portions from a direction vertical to a pair of said flat plate portions; and
20 accommodating portions which are formed to said drum portion except said bearing portion and accommodate therein a drying agent.

18. A carrier reel comprising:

25 a flange portion having a first surface and a second surface which is opposed to and substantially parallel to said first surface;

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a hub portion which is provided between said first surface and said second surface and to which said flange portion is connected;

5 a carrier tape which is wound around said hub portion and in which a plurality of semiconductor devices are stored;

10 a bearing portion which is formed in the center of said hub portion and associated with a shaft supporting a pair of said flange portions from a direction vertical to a pair of said flange portions; and

accommodating portions which are formed to said hub portion except said bearing portion and accommodate therein a drying agent.

15 19. The carrier reel according to claim 17, wherein said accommodating portions are provided symmetrical to said bearing portion.

20 20. The carrier reel according to claim 18, wherein said accommodating portions are provided symmetrical to said bearing portion.

25 21. A method for manufacturing an electronic component according to claim 17 further comprising, taking out a carrier reel from a bag in which said carrier reel, and putting to mount said electronic component on a board.

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22. A method for manufacturing an electronic component according to claim 18 further comprising, taking out a carrier reel from a bag in which said carrier reel, and putting to mount said electronic component on a board.

5 23. The method for manufacturing an electronic component according to claim 21, wherein said electronic component is a semiconductor device sealed by resin and said step of mounting said electronic component on said board is carried out by heat treatment.

10 24. The method for manufacturing an electronic component according to claim 22, wherein said electronic component is a semiconductor device sealed by resin and said step of mounting said electronic component on said board is
15 carried out by heat treatment.

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